		PAPER TITLE	**AUTHOR**	**Company**
Session ID / Paper	**Time**	**Technical Sessions**	**Session Chair**	**Session Co-Chair**
	AM	**Counterfeit- Prevention & Mitigation Strategies**	Aaron DerMardersosian	S. Ali Lilani
A		**Seminar Room**	aaron_dermarderosian_jr@raytheon.com	Sultan.Lilani@integra-tech.com
1	8:30-8:55	An Update on the Authentication Platform DLA has Selected as Part of their Counterfeit Prevention Effort	Janice Meraglia	Applied DNA Sciences
2	8:55-9:20	Defense Electronic - Trends	Tina Barcley	TAS Consulting
3	9:20-9:45	Counterfeit Analysis Supply Chain Case Studies - Counterfeit Detection & Quality Control Non Conformance Issues	Aaron DerMardersosian, Jr.	Raytheon Company
	BREAK			
4	10:15-10:40	Ceramic Taggants for Authentication or Provenance Marking of Electronic Components	Dr. Arthur Jonath, Jr.	Arthur Jonath Associates
5	10:40-11:05	Save Time and Money by Carefully Selecting Plastic Packaged Integrated Circuits	S. Ali Lilani	Integra Techchnologies
	AM	**RF and Microwave - Innovations and Emerging Technologies - Part I**	Tom Terlizzi	Larry Hawkins
B		**Colonial Room**	terlizzi@gmsystems.com	Larry.Hawkins@analog.com
1	8:30-8:55	The Current State of Integration in IC's	Larry Hawkins	Analog Devices Inc.
2	8:55-9:20	Packaging Technologies Behind GaN Power Transistors for High Power S-Band Radar Applications	Chris Hermanson	Cree, Inc.
3	9:20-9:45	High Temperature Cofired Ceramic (HTCC) Package Design and Applications	Ken McGillivray	HCC Electronic Packaging - (Aegis Ametek)
	BREAK			
4	10:15-10:40	Optimization of Tin Vapor Deposition Process on Tungsten-Copper Substrate	Sanchayan Dutta	Santier
5	10:40-11:05	High Reliability Designs and Manufacturing of RF Components and Assemblies	Chandra Gupta	Hittite Microwave Corp.
6	11:05-11:30	GaN Doherty Amplifiers for Commercial and Military Applications	Tom Kelly	NXP Semiconductors
	AM	**Bumped Die Attach**	Jim McLenaghan	Dan Baldwin
C		**Cotillion Room**	ajm@creyr.net	dan.baldwin@engentaat.com
1	8:30-8:55	Next Generation Assembly Structures using Copper Wire Bonding Interconnection	Dr. Dan Baldwin	Engent, Inc.
2	8:55-9:20	Process Development for Ball Grid Array Attachment on DuPont™ Green Tape™ 9K7 LTCC	Allan Beikmohamadi	DuPont Microcircuit Materials
3	9:20-9:45	Thermo-Sonic Flip Chip Methods on Copper or Solder Interconnect Structures	Tae Yi	Panasonic Factory Solutions Co., LTD
	BREAK			
4	10:15-10:40	Reliability Issues in Flip Chip Design	Ed Dodd	DfR Solutions
5	10:40-11:05	Using Solid State Micro-Batteries in Flip-Chip Applications	Jeff Sather	Cymbet Corp
6	11:05-11:30	Selecting Stencil Technologies to Optimize Print Performance	Chrys Shea	Shea Engineering
	AM	**NANO and MEMS**	Dr. Alan Rae	Matt Apanius
D		**Directors Room**	arae@nanomic.org	matt@smartmicrosystems.com
1	8:30-8:55	From Automotive Crash Sensing to Consumer Electronics and Beyond	Rob O'Reilly	MEMS Sensor and Technology Group, Analog Devices, Inc.
2	8:55-9:20	Advances in Thin, 3D and MEMS Die Bond Strength Testing	Bob Sykes	XYZTECbv
3	9:20-9:45	Nanomanufacturing and Electronics	Alan Rae	NanoMaterials Innovation Center, LLC
	BREAK			
4	10:15-10:40	Optical Leak Testing of MEMS Devices	Chris Aubertin	Norcom Systems Inc.
5	10:40-11:05	Alternative Miniature Vibration Sensor Technology	Dr. Atul Pradhan	Micatu, Inc.
		Keynote Lunch Speaker		
		Restoring Vision with Subretinal Implants	**Dr. Timo Lebold**	**Retina Implant AG**

		PAPER TITLE	AUTHOR	Company
Session ID / Paper	**Time**	**Technical Sessions**	**Session Chair**	**Session Co-Chair**
	PM	**Wire Bonding & Advanced Interconnections (Cu)**	Bill Boyce	
E		**Seminar Room**	wboyce@sensata.com	
1	1:00-1:25	Design & Process Considerations to Avoid Resonance Induced Heel Cracks during an Ultrasonic Wire Bond Process	James Card	Sensata Technologies
2	1:25-1:50	Aluminum and Copper Wire Bonding to ENIG and ENEPIG	George Milad	Uyemura International Corp.
3	1:50-2:15	Configurations for Robust Gold Stitch-to-Substrate Wire Bond Attachment – Part 2	Ashley Hlavacik	Desich SMART Center
4	2:15-2:40	Heavy Copper Wedge Bonding in Power Electronics	Dr. Michael Broekelmann	Hesse Mechatronics, Inc.
5	2:40-3:05	Reworkable Interconnects using Alternative Materials	Dr Michael C. Hamilton	Auburn University
	PM	**RF and Microwave - Innovations and Emerging Technologies - Part II**	Tom Terlizzi	Larry Hawkins
F1		**Colonial Room**	terlizzi@gmsystems.com	Larry.Hawkins@analog.com
1	1:00-1:25	Non-Hermetic Packaging of RF Microwave Modules	Matt Gruber	Lockheed Martin
2	1:25-1:50	A High Performance Single Component Conductive Epoxy for Inter-Connecting Silicon Stacked Die Layers - And a New Development for Globtop	Samuel Forman	Microcoat Techologies
	PM	**Novel Technologies**	Dmitry Marchenko	
F2		**Colonial Room**	dmitry.marchenko@microsemi.com	
3	1:50-2:15	Development of Low Temperature Sintered Nano Silver Pastes Using MO Technology and Resin Reinforcing Technology	Tony Tuscigno	NAMICS Technologies
4	2:15-2:40	Design and Fabrication of a Highly Integrated Silicon Detector for the STAR Experiment at Brookhaven National Laboratories	Benjamin Buck	MIT/Brookhaven Laboratories
5	2:40-3:05	Packaging and Ceramic Feedthroughs for the Boston Retinal Prosthesis	Tom Salzer	Hermetric Inc.
	PM	**Technologies and Methods for 2.5/3D Packaging**	Ken Aruajo	Maria Durham
G		**Cotillion Room**	araujo@namics-usa.com	mdurham@indium.com
1	1:00-1:25	Pre-Applied Materials for 2.5/3D Technology	Tony Tuscigno	NAMICS Technologies
2	1:25-1:50	Progress in Fabrication and Test of Glass Interposer Substrates	Aric Shorey	Corning, Inc.
3	1:50-2:15	Comparison of Measured and Modeled Lithographic Process Capabilities for 2.5D and 3D Applications Using a Step and Repeat Camera	James Webb	Rudolph Technologies, Inc.
4	2:15-2:40	Recent Advances in Die Attach Film and Temporary Wafer Protection	Frederick Lo	AI Technology Inc
5	2:40-3:05	Evaluating Underfill Material for 3D Integration of High Density Heterogeneous Sensor Arrays	Chris Gregory	RTI International
	All Day	**Poster Session**	Dr. Wei Han	Dr. Rita Mohanty
H		**Federal Room / Registration Area**	weihan.vivian@gmail.com	ritam1010@hotmail.com
1		The Effect of Current Density on the Grain Size and Surface Morphology of Electrodeposited Pt Nanowires	Dajiang Ruan	Department of Chemical Engineering University of Massachusetts Lowell
2		Low Temperature Soldering Using Tin/Indium (Sn/In) Lead-free Nanosolders	Yang Shu	Department of Chemical Engineering University of Massachusetts Lowell
3		Microfluidic Synthesis of Lead-free Nanosolder Particles	Zhiyang Li	Department of Chemical Engineering University of Massachusetts Lowell
4		PCA Environmental Compliance and Verification Tools	Scott Mazur	Benchmark Electronics-NH
5		Hydrogen for Small Scale Semiconductor Fabrication and Packaging	Dave Wolff	Proton On Site
6		Criteria for Selecting a Solder Paste and Troubleshooting Common Challenges	Derrick Herron	Indium Corporation, NY
7		Packaging of GaAs Chips for Use in RF MCM Products	Caroline K. Bjune	Draper Laboratory
8		Additive Manufacturing for Biomedical Applications	Jianyu Liang	Worchester Polytechnic Institute
9		Cold Spray for Enabling Innovaitons in Electronics	Jianyu Liang	Worchester Polytechnic Institute